Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]
HP EliteOne 1000 G2 34-in Curved All-in-One Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Motherboard, RAM</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries RTC battery</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>EPS, Power Cord</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at EL-MF877-01
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>TORX T8</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Removed Base Top Cover
2. Removed Base Front Cover
3. Removed Power Switch Board, Sensor Board
4. Remove 4 screws then disassembly the LID (LCD chassis)
5. Removed Fan Module
6. Removed Heat Sink
7. Removed Stand Arm Base, MB Protect Cover
8. Removed Side I/O Top Shielding
9. Remove SSHD
10. Removed Speaker module
11. Removed Wireless Card, Ram, CPU
12. Removed RTC battery
13. Removed Motherboard, Bottom Base Cover
14. Removed Stand Rear Cover, Stand Front Cover
15. Removed Stand Arm
16. Removed Rear Cover
17. Removed Hinge Stand, OSD board
18. Removed Scalar Shielding, Scalar Board, Scalar Bracket Bottom
19. Removed Camera Box, Camera Transfer Board
20. Removed Camera Module, Camera Bracket, DMIC Board, RGB Camera Box Cable
21. Removed Camera Holder, LCD Frame
22. Removed LCD Chin, LCD Chin Bracket, LCD Panel

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Removed Base Top Cover
2. Removed Base Front Cover

3. Removed Power Switch Board, Sensor Board

4. Remove 4 screws then disassembly the LID (LCD chassis)

5. Removed Fan Module
6. Removed Heat Sink

7. Removed Stand Arm Base, MB Protect Cover

8. Removed Side I/O Top Shielding

9. Remove SSHD
10. Removed Speaker module

11. Removed Wireless Card, Ram, CPU

12. Removed RTC battery
13. Removed Motherboard, Bottom Base Cover

14. Removed Stand Rear Cover, Stand Front Cover

15. Removed Stand Arm
16. Removed Rear Cover

17. Removed Hinge Stand, OSD board

18. Removed Scalar Shielding, Scalar Board, Scalar Bracket Bottom
19. Removed Camera Box, Camera Transfer Board

20. Removed Camera Module, Camera Bracket, DMIC Board, RGB Camera Box Cable

21. Removed Camera Holder
22. Removed LCD Chin, LCD Chin Bracket, LCD Frame, LCD Panel